# **Product Specification**

(Preliminary)

Part Name: OEL Display Module Part ID: UG-2828GDEDF02

Doc No.: SAS1-XXXX-A

Customer:			
Approved by			

From: Univision Technology Inc.				
Approved by				

## Univision Technology Inc.

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# Revised History

Part Number	Revision	Revision Content	Revised on	
UG-2828GDEDF02	A	New	May 4, 2006	

Doc. No: SAS1-XXXX-A



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### 1. Basic Specifications

#### 1.1 Display Specifications

1) Display Mode: Passive Matrix

2) Display Color: 262,144 Colors (Maximum)

3) Drive Duty: 1/128 Duty

#### 1.2 Mechanical Specifications

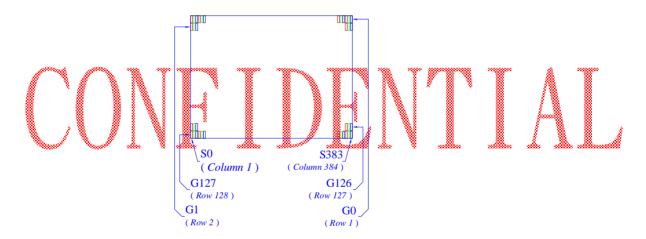
1) Outline Drawing: According to the annexed outline drawing number

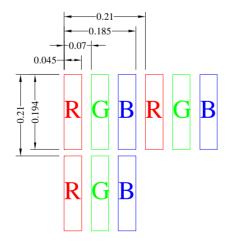
2) Number of Pixels:  $128(RGB) \times 128$ 

3) Panel Size: 33.80 × 34.00 × 1.70 (mm)
 4) Active Area: 26.855 × 26.864 (mm)
 5) Pixel Pitch: 0.07 × 0.21 (mm)
 6) Pixel Size: 0.045 × 0.194 (mm)

7) Weight: 4.0 (g)

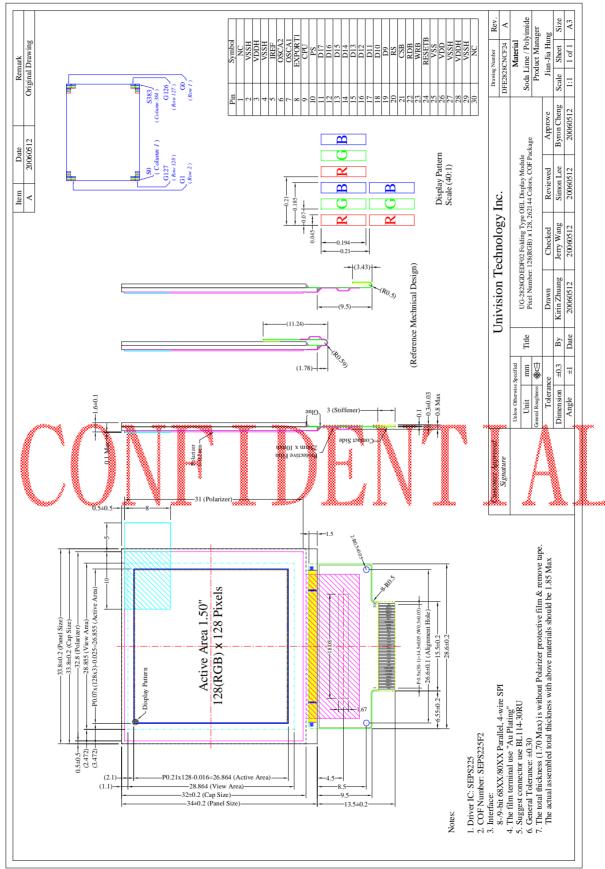
#### 1.3 Active Area & Pixel Construction





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#### 1.4 Mechanical Drawing



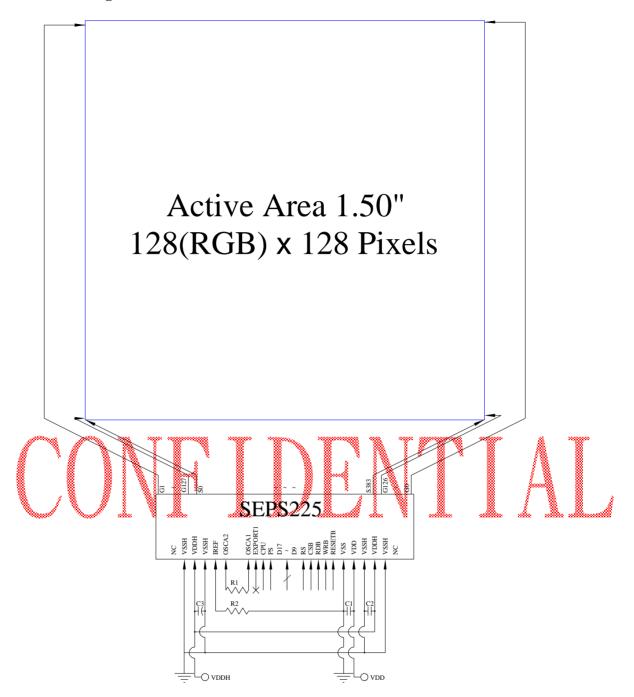


### 1.5 Pin Definition

Ī	Pin Number	Symbol	Туре	Function
	2,4,27,29	VSSH	P	Return Ground for VDDH
	3,28	VDDH	P	External Column Driving Power Supply.
	25	VSS	P	Power supply ground
	26	VDD.	P	Logic power supply.
	5	IREF	I/O	Current Reference for Brightness Adjustment Tie $68K\Omega$ resistor to VSS.
	6	OSCA2	О	Fine adjustment for oscillation
	7	OSCA1	I	Tie $10 \text{ K}\Omega$ resistor to OSCA1 between OSCA2. When the external clock mode is selected, OSCA1 is used external clock input.
	8	EXPORT1	О	OSC Test
	9	CPU	I	Selects the CPU type Low: 80-series CPU, High: 68-Series CPU.
	10	PS	I	Selects parallel/Serial interface type  Low: serial, High: parallel.
				Host Data Input/Output Bus  These pins are 9-bit bi-directional data bus to be connected with MCU data bus.  PS Description
	11~19	D17~D9	I/O	1 8_bit bus : D[17:10] 9_bit bus : D[17:9]
				D[17 SCL : Synctronous clock input 0 D[16] SDL : Serial data input D[15] SDO: Serial data output Ex unused pms to the VSS level.
*	20	RS	4	Selects the data/command  Low: command, High: parameter/data
	21	CSB	I	Chip Select Low: SEPS225 is selected and can be accessed. High: SEPS225 is not selected and cannot be accessed.
	22	RDB	I	Read or Read/Write Enable 80-system bus interface: read strobe signal (active low). 68-system bus interface: bus enable strobe (active high). When serial mode, fix it to VDD or VSS level.
	23	WRB	I	Write or Read/Write Select  80-system bus interface: write strobe signal (active low).  68-system bus interface: read/write select.  Low: write, High: read.  When serial mode, fix it to VDD or VSS level.
	24	RESETB	I	Chip Reset Reset SEPS225 (active low)
	1,30	NC	_	No Connection



#### 1.6 Block Diagram



MCU Interface Selection: PS, CPU

Pins connected to MCU interface: D17~D9, RDB, RS, CSB, WRB, and RESB

\* EXPORT1would be left float.

C1:  $1\mu F$  C2, C3:  $4.7\mu F$  R1:  $10k\Omega$  R2:  $68k\Omega$ 



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### 2. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage	VDD	-0.3	4	V	1, 2
Driver Supply Voltage	VDDH	-0.3	19.5	V	1, 2
Operating Temperature	$T_{\mathrm{OP}}$	-30	70	°C	-
Storage Temperature	$T_{STG}$	-40	80	°C	-

Note 1: All the above voltages are on the basis of "GND = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

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#### 3. Electrical Characteristics

#### 3.1 DC Characteristics

Characteristics	Symbol	Conditions	Min	Тур	Max	Unit
Supply Voltage	VDD		2.6	2.8	3.3	V
Driver Supply Voltage	VDDH		-	13	-	V
High Level Input	$V_{\mathrm{IH}}$		0.8×VDD	-	VDD	V
Low Level Input	$V_{ m IL}$		0	-	0.4	V
High Level Output	$V_{\mathrm{OH}}$		VDD-0.4	-	-	V
Low Level Output	$V_{OL}$		-	1	0.4	V

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#### 3.2 AC Characteristics

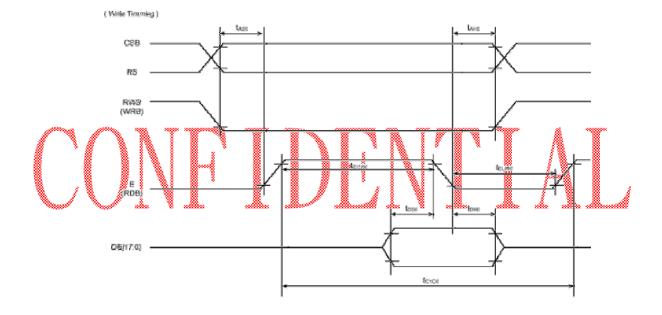
3.2.1 68XX-Series MPU Parallel Interface Timing Characteristics:

 $(VDD = 2.8V, Ta = 25^{\circ}C)$ 

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Symbol	Description	Condition	Min	Max	Unit	Port
t <sub>AH6</sub>	Address hold timing	-	5	-	ns	CSB
t <sub>AS6</sub>	Address setup timing	-	5	-	ns	RS
t <sub>CYC6</sub>	System cycle timing	-	100	-	ns	
t <sub>WRLW6</sub>	Write "L" pulse width	_	45	_	ns	Е
t <sub>WRHW6</sub>	Write "H" pulse width	_	45	_	ns	
$t_{\rm DS6}$	Data setup timing	-	40	-	ns	DB[17:01
t <sub>DH6</sub>	Data hold timing	-	10	_	ns	DB[17:0]

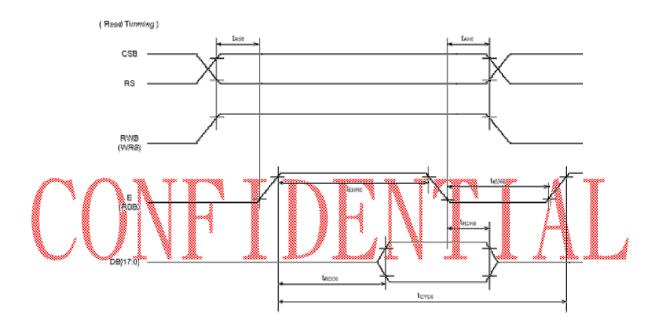
<sup>\*</sup>All the timing reference is 10% and 90% of VDD.





				DD - 2		• /
Symbol	Description	Condition	Min	Max	Unit	Port
t <sub>AH6</sub>	Address hold timing	-	10	-	ns	CSB
t <sub>AS6</sub>	Address setup timing	-	10	1	ns	RS
t <sub>CYC6</sub>	System cycle timing	-	200	ı	ns	
$t_{RDLR6}$	Read "L" pulse width	-	90	ı	ns	RDB
t <sub>RDHR6</sub>	Read "H" pulse width	-	90	-	ns	
t <sub>RDD6</sub>	Read data output delay time	CL = 15 pF	0	70	ns	DB[17:0]
t <sub>RDH6</sub>	Data hold timing	1			ns	

<sup>\*</sup>All the timing reference is 10% and 90% of VDD.

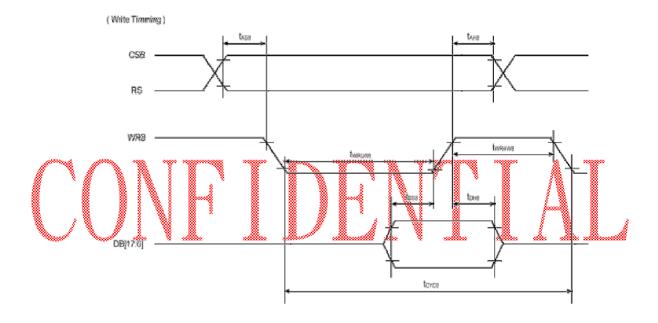




# 80XX-Series MPU Parallel Interface Timing Characteristics:

T						
Symbol	Description	Condition	Min	Max	Unit	Port
$t_{AH8}$	Address hold timing	-	5	-	ns	CSB
$t_{AS8}$	Address setup timing	_	5	_	ns	RS
t <sub>CYC8</sub>	System cycle timing	_	100	_	ns	
t <sub>WRLW8</sub>	Write "L" pulse width	-	45	-	ns	WRB
t <sub>WRHW8</sub>	Write "H" pulse width	_	45	_	ns	
$t_{ m DS8}$	Data setup timing	_	30	_	ns	DD[17:0]
$t_{\mathrm{DH8}}$	Data hold timing	-	10	-	ns	[0:/1]פען

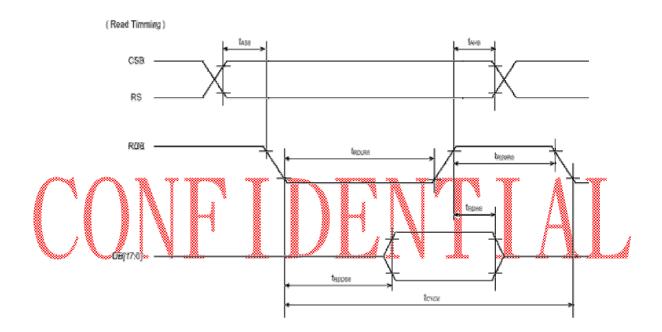
<sup>\*</sup>All the timing reference is 10% and 90% of VDD.





						- /
Symbol	Description	Condition	Min	Max	Unit	Port
$t_{AH8}$	Address hold timing	-	5	-	ns	CSB
t <sub>AS8</sub>	Address setup timing	-	5	-	ns	RS
t <sub>CYC8</sub>	System cycle timing	-	200	-	ns	
$t_{RDLR8}$	Read "L" pulse width	_	90	_	ns	RDB
t <sub>RDHR8</sub>	Read "H" pulse width	_	90	-	ns	
t <sub>RDD8</sub>	Read data output delay time	CL = 15 pF	-	60	ns	DB[17:0]
$t_{\rm RDH8}$	Data hold timing	1	0		ns	

<sup>\*</sup>All the timing reference is 10% and 90% of VDD.



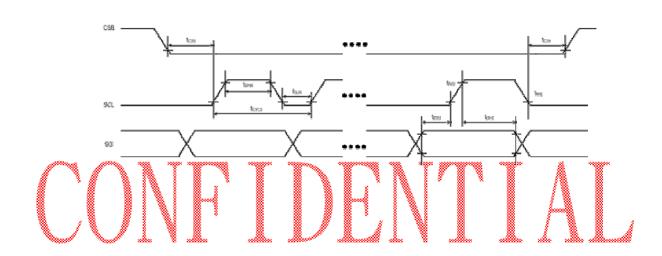


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# 3.2.3 Serial Interface Timing Characteristics:

Symbol	Description	Condition	Min	Max	Unit	Port
t <sub>CYCS</sub>	Serial clock cycle	-	60	-	ns	
$t_{ m SHW}$	SCL "H" pulse width	-	25	-	ns	SCL
$t_{\rm SLW}$	SCL "L" pulse width	-	25	-	ns	
$t_{\rm DSS}$	Data setup timing	-	25	-	ns	SDI
$t_{DHS}$	Data hold timing	-	25	-	ns	SDI
$t_{CSS}$	CSB-SCL timing	-	25	-	ns	CSB
$t_{CSH}$	CSB-hold timing	-	25	-	ns	СЗБ

<sup>\*</sup>All the timing reference is 10% and 90% of VDD.



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#### 3.3 Optics & Electrical Characteristics

Characteristics	Symbol	Conditions	Min	Тур	Max	Unit
Brightness (White)	$L_{br}$	With Polarizer (Note 3)	70	90	1	cd/m <sup>2</sup>
C.I.E. (White)	(x)	With Polarizer	0.24	0.28	0.32	
0.1.2. ( , ,	(y)	, , 1011 1 0 1001 12 0 1	0.29	0.33	0.37	
C.I.E. (Red)	(x)	With Polarizer	0.60	0.64	0.68	
C.I.E. (Reu)	(y)	With I Old izei	0.31	0.35	0.39	
CIE (Graan)	(x)	With Polarizer	0.26	0.30	0.34	
C.I.E. (Green)	(y)	Willi Polarizei	0.61	0.65	0.69	
CIE (Dluc)	(x)	With Polarizer	0.10	0.14	0.18	
C.I.E. (Blue)	(y)	with Polarizer	0.15	0.19	0.23	
Dark Room Contrast	CR		-	>1000:1	-	
View Angle			>160	-	-	degree

<sup>\*</sup> Optical Measurement Follow the Software Initial Setting with Sec. 4.4 "Initial Sequence & Setting Value"

#### 3.4 General Electrical Specification

Characteristics	Symbol	Conditions	Min	Тур	Max	Unit
Supply Voltage	$V_{\mathrm{DD}}$		2.6	2.8	3.5	V
Supply Voltage for // // // // // // // // // // // // //	$V_{\mathrm{DDIO}}$		1.5	2.8	3.5	V
Driver Supply Voltage	$ m V_{Cc}$	Nøte 3	-	13	-	V
Operating Current for	T	Nøte 4	-	2.5	3.5	mA
V <sub>D</sub> D.	IDD	Note 5		. 2.5	-3. <b>5</b>	mΑ
Operating Current for	ī	Note 4	-	19	23	mA
$V_{CC}$	$I_{CC}$	Note 5	-	30	36	mA
Sleep Mode Current for $V_{\mathrm{DD}}$	I <sub>DD, SLEEP</sub>		-	<1	1	μΑ
Sleep Mode Current for $V_{\rm DDH}$	$I_{\text{DDH,SLEEP}}$		-	<1	1	μΑ

Note 3: Brightness ( $L_{br}$ ) and Driver Supply Voltage ( $V_{CC}$ ) are subject to the change of the panel characteristics and the customer's request.

Note 5:  $V_{DD}$  = 2.8V,  $V_{CC}$  = 13V, Test condition follow Sec.4.4 "Initial Sequence & Setting Value", 100% Display Area Turn on.

Note 4:  $V_{DD}$  = 2.8V,  $V_{CC}$  = 13V, Test condition follow Sec.4.4 "Initial Sequence & Setting Value", 50% Display Area Turn on.

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#### 4. Functional Specification

#### 4.1. Commands

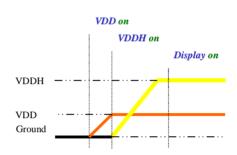
Refer to the Technical Manual for the SEPS225

#### 4.2 Power down and Power up Sequence

To protect OEL panel and extend the panel life time, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off. It gives the OEL panel enough time to complete the action of charge and discharge before/after the operation.

#### 4.2.1 Power up Sequence:

- 1. Power up VDD
- 2. Send Display off command
- 3. Clear Screen
- 4. Power up VDDH
- 5. Delay 100ms (when VDD is stable)
- 6. Send Display on command



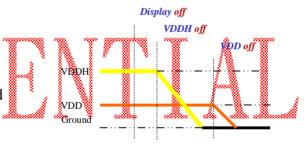
#### 4.2.2 Power down Sequence:

l. Send Display off command

Power down VDDH

3. Delay 100ms when VDDH is reach 0 and panel is completely discharges)

4. Power down VDD



#### 4.3 Reset Circuit

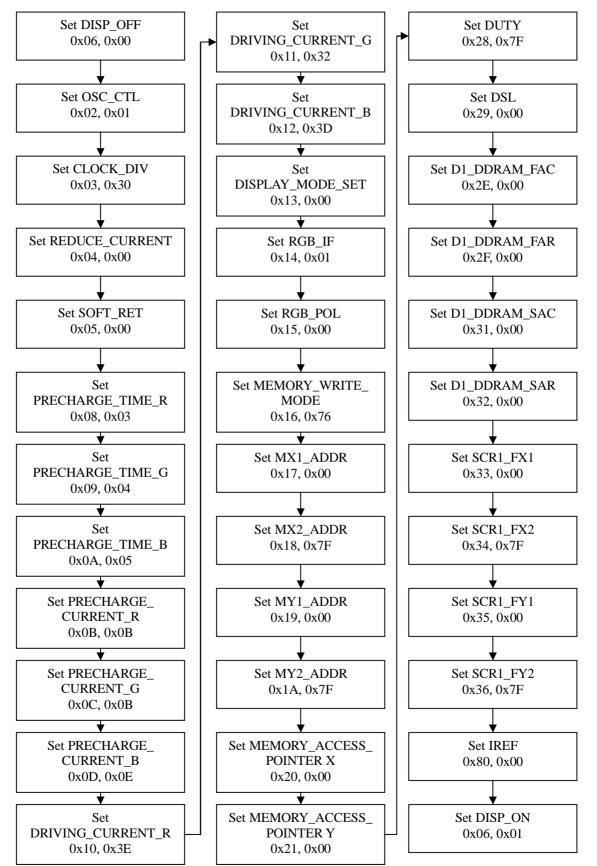
When RESETB input is low, the chip is initialized with the following status:

- 1. Frame frequency: 90Hz
- 2. OSC: internal OSC
- 3. Internal OSC: ON
- 4. DDRAM write horizontal address: MX1 = 00h, MX2 = 7Fh
- 5. DDRAM write vertical address: MY1 = 00h, MY2 = 7Fh
- 6. Display data RAM write: HC = 1, VC = 1, HV = 0
- 7. RGB data swap: OFF
- 8. Row scan shift direction: G0, G1, ..., G126, G127
- 9. Column data shift direction: S0, S1, ..., S382, S383
- 10. Display ON/OFF: OFF
- 11. Panel display size: FX1 = 00h, FX2 = 7Fh, FY1 = 00h, FY2 = 7Fh
- 12. Display data RAM read column/row address: FAC = 00h, FAR = 00h
- 13. Precharge time(R/G/B): 0 clock
- 14. Precharge current(R/G/B): 0 uA
- 15. Driving current(R/G/B): 0 uA

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#### 4.4 Actual Application Example

Initial Sequence & Setting Value:



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## 5. Reliability

#### 5.1 Contents of Reliability Tests

Item	Conditions	Criteria
High Temperature Operation	70°C, 240 hrs	
Low Temperature Operation	-30°C, 240 hrs	
High Temperature Storage	80°C, 240 hrs	
Low Temperature Storage	-40°C, 240 hrs	The operational functions work.
High Temperature/Humidity Operation	60°C, 90% RH, 120 hrs	functions work.
Thermal Shock	$-40$ °C $\Leftrightarrow$ 85°C, 24 cycles 1 hr dwell	

<sup>\*</sup> The samples used for the above tests do not include polarizer.

#### 5.2 Lifetime

End of lifetime is specified as 50% of initial brightness.

Parameter	Min	Max	Unit	Condition	Notes
Operating Life Time	10,000	-	Hrs	70 cd/m <sup>2</sup> , 50% checkerboard	6
Storage Life Time	20,000	-	Hrs	ta=25°C, 50% RH	-

Note 6: The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

#### 5.3 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.

<sup>\*</sup> No moisture condensation is observed during tests.



### 6. Outgoing Quality Control Specifications

#### 6.1 Environment Required

Customer's test & measurement are required to be conducted under the following conditions:

Temperature:  $23 \pm 5^{\circ}\text{C}$ Humidity:  $55 \pm 15 \text{ }\%\text{RH}$ 

Fluorescent Lamp: 30W Distance between the Panel & Lamp:  $\geq 50 \text{ cm}$  Distance between the Panel & Eyes of the Inspector:  $\geq 30 \text{ cm}$ 

Finger glove (or finger cover) must be worn by the inspector.

Inspection table or jig must be anti-electrostatic.

#### 6.2 Sampling Plan

Level II, Normal Inspection, Single Sampling, MIL-STD-105E

#### 6.3 Criteria & Acceptable Quality Level

Partition	AQL	Definition
Major 0.65		Defects in Pattern Check (Display On)
Minor 1.0		Defects in Cosmetic Check (Display Off)

## 6.3.1 Cosmetic Check (Display Off) in Non-Active Area

Check Item	Classification	Criteria
Panel General Chipping	Minor	X > 6 mm (Along with Edge) Y > 1 mm (Perpendicular to edge)



6.3.1 Cosmetic Check (Display Off) in Non-Active Area (Continued)

Check Item	Classification	Criteria
Panel Crack	Minor	Any crack is not allowable.
Cupper Exposed (Even Pin or Film)	Minor	Not Allowable by Naked Eye Inspection
Film or Trace Damage	Minor	CO. N
		Not Allowable  D. TVISTED LEAD
Terminal Lead Twist	Minor	
Terminal Lead Broken	Minor	Not Allowable  A. BROKEN LEAD
Terminal Lead Probe Mark	Acceptable	Ok



6.3.1 Cosmetic Check (Display Off) in Non-Active Area (Continued)

	Check Item	Classification	Criteria
	Terminal Lead Bent	Minor	NG if any bent lead cause lead shorting.
1)	Not Twist or Broken)	Minor	NG for horizontally bent lead more than 50% of its width.
Same	lae or Contamination on Pin Couldn't Be Removed by Alcohol)	Minor	
I	nk Marking on Back Side of panel (Exclude on Film)	Acceptable	Ignore for Any



## 6.3.2 Cosmetic Check (Display Off) in Active Area

It is recommended to execute in clear room environment (class 10k) if actual in necessary.

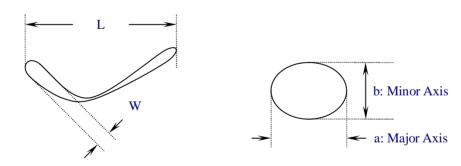
Check Item	Classification	Criteria	
Any Dirt & Scratch on Protective Film	Acceptable	Ignore for A	ny
Scratches, Fiber, Line-Shape		$W \le 0.1$	Ignore
Defect	Minor	W ≤ 0.1	Ignore
(On Polarizer)		$W > 0.1, L \le 2$	n ≤ 1
		L > 2	n = 0
Dirt, Spot-Shape Defect		$\Phi \le 0.1$	Ignore
(On Polarizer)	Minor	$0.1 < \Phi \le 0.25$	n ≤ 1
(On Foldinger)		0.25 <Φ	n = 0
Dent, Bubbles, White spot (Any Transparent Spot on Polarizer)	Minor	Φ ≤ 0.5 <b>è</b> Ignore if no Into Display 0.5 < Φ	fluence on $n = 0$
Fingerprint, Flow Mark (On Polarizer)	Minor	Not allowat	ole



<sup>\*\*</sup> Definition of W & L & Φ (Unit: mm):

$$\Phi = (a+b)/2$$

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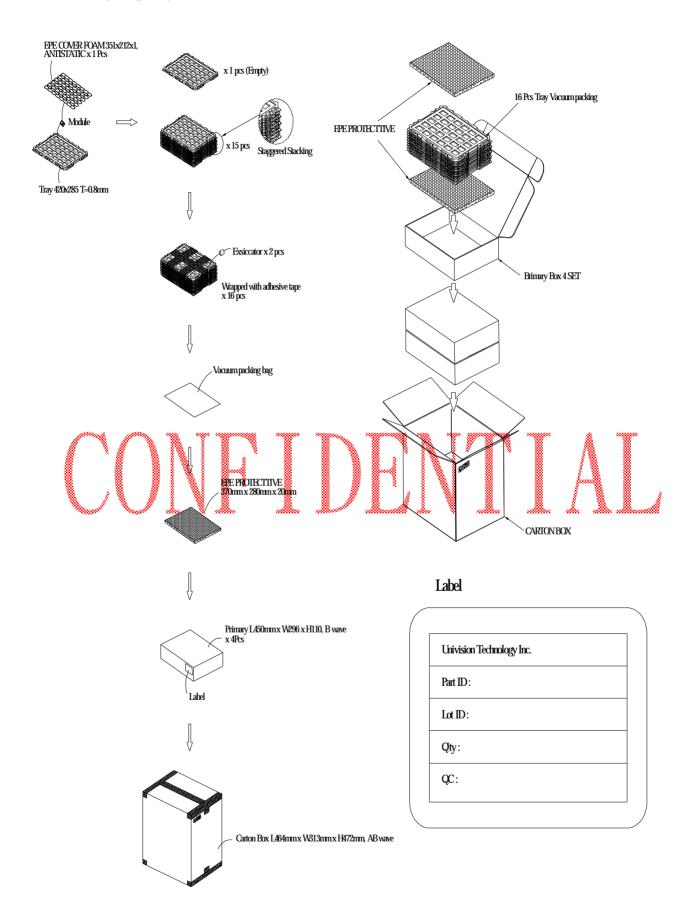
6.3.3 Pattern Check (Display On) in Active Area

	Check Item	Classification	Criteria
	No Display	Major	Not allowable
	Bright Line	Major	
	Missed Line	Major	
	Pixel Short	Major	
	Darker Pixel	Major	•
	Wrong Display	Major	
	Un-Uniform (Luminance Variation within a Display)	Major	



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## 7. Package Specifications





8. Precautions When Using These OEL Display Modules

#### 8.1 Handling Precautions

1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.

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- 2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- 3) If pressure is applied to the display area, both of top and back sides, or its neighborhood of the OEL display module, the cell structure may be damaged and be careful not to touch these sections on carrying and assembly.
- 4) The polarizer covering the surface of the OEL display module is soft and easily scratched. Please be careful when handling the OEL display module.
- 5) When the surface of the polarizer of the OEL display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
  - \* Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- \* Water
- \* Ketone
- \* Aromatic Solvents
- When installing the OEL display module, be careful not to apply twisting stress or deflection stress to the OEL display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient regidity for the outer cases.
- 7) Do not appty stress to the LSI chips and the surrounding molded sections:
- 8) Do not disassemble nor modify the ØEL display module.
- 9) Do not apply input signals while the logic power is off.
- 10) Pay sufficient attention to the working environments when handing OEL display modules to prevent occurrence of element breakage accidents by static electricity.
  - \* Be sure to make human body grounding when handling OEL display modules.
  - \* Be sure to ground tools to use or assembly such as soldering irons.
  - \* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
  - \* Protective film is being applied to the surface of the display panel of the OEL display module. Be careful since static electricity may be generated when exfoliating the protective film.
- 11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OEL display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5).
- 12) If electric current is applied when the OEL display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.



#### 8.2 Storage Precautions

When storing OEL display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps, etc. and, also, avoiding high temperature and high humidity environments or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Univision Technology Inc.)

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- At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- 2) If electric current is applied when water drops are adhering to the surface of the OEL display module, when the OEL display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

#### **8.3 Designing Precautions**

- 1) The absolute maximum ratings are the ratings which cannot be exceeded for OEL display module, and if these values are exceeded, panel damage may be happen.
- 2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- 3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- 4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- 5) As for EMI take necessary measures on the equipment side basically.
- 6) When fastening the OEL display module fasten the external mastic housing section.
- 7) If power supply to the OEL display module is forcibly shut down by such errors as taking out the main battery while the OEL display panel is in operation, we cannot guarantee the quality of this OEL display module.
- 8) The electric potential to be connected to the rear face of the IC chip should be as follows: SSPS225
  - \* Connection (contact) to any other potential than the above may lead to rupture of the IC.

#### 8.4 Precautions when disposing of the OEL display modules

1) Request the qualified companies to handle industrial wastes when disposing of the OEL display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

#### **8.5** Other Precautions

1) When an OEL display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur.

Nonetheless, if the operation is interrupted and left unused for a while, normal



state can be restored. Also, there will be no problem in the reliability of the module.

- 2) To protect OEL display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OEL display modules.
  - \* Pins and electrodes
  - \* Pattern layouts such as the COF
- 3) With this OEL display module, the OEL driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OEL driver is exposed to light, malfunctioning may occur.
  - \* Design the product and installation method so that the OEL driver may be shielded from light in actual usage.
  - \* Design the product and installation method so that the OEL driver may be shielded from light during the inspection processes.
- 4) Although this OEL display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.
- 5) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.

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